Si Wafers



cifications

Diameter, mm	100
Thickness, µm	380; 420; 460
Deviation from nominal value, µm	± 25
ystallographic orientation, °	(100); (111)
pant	B or P
pe	onocrystalline silicon wafers KDB or KEF
Flat orientation	SEMI EJ
Polishing	ouble-sided
TTV minimum, µm	2
TTV minimum/standard, µm	p to 5